Developing rad-hard Chip-on-Board Fiber-Optics https://indico.phys.sinica.edu.tw/event/104/



#### Fiber rad-hard MM Ge-doped Co60 TID

- Opto CMOS rad-hard 850 nm VCSEL, PD NIEL, TID
- HEP opticl links

experience, future Chip-on-Board assembly









suen@sinica.edu.tw 侯書雲 2024.06.19

# **Optical fiber making**

PCVD plasma chemical vapor Deposition MCVD modified chemical vapor deposition OVD outside vapor deposition VAD vapor axial deposition Fused Silica Tubes, pure SiO<sub>2</sub> for Fiber Optics,



Bare Fiber Reel

Fiber Cable



Looking for testing 武漢 YOFC <u>长飞光纤</u> Ge-doped, Rad-hard fibers



## Light Coupling efficiency

 VCSEL far-field distribution at low current, 0<sup>th</sup> mode is centralized higher modes pop-up in outer-rings wider angles

#### - Coupling to Lens

loss to reflection, angular acceptance



#### L-I, FOCI lens coupled







VCSEL+Lens in Oven







#### Far-field angle vs I, T

Fiber Co-60 TID test

Bare fiber sample in bag, with SC connectors in water bath, online DAQ at const °C



water cooling





## Ge-doped MM fiber, Co-60 test

Fiber Radiation Induced Attenuation (RIA)

RIA = (IL(0) - IL(t))/LengthIL(dB) =  $10 \times log10 (P_T/P_R)$ 

IL insertion loss P<sub>T</sub> transmitter, P<sub>R</sub> received

Dependences : Dose rate, Temperature

Fibers tested at Dose rate 1.5kGy/hr Irrad ~8hr daytime, anneal overnight, over 1 week





## TID effects on CMOS

**Total Ionizing Dose (TID)** induces charge-trapping at **Si-SiO2 interface Dependence :** total dose, dose rate, annealng

- new interface states formed.
- interface state density vs. energy changed
- interface state density changes with time
- construction after irradiation
- static and dynamic electrical response of the Si-SiO2 altered





Charge trapped at the interface

Threshold voltage degradation as a function of the total Dose

## X-ray TID on MTX LOCID of ATLAS LAr

#### X-ray, 3 dose-rates in 280 min to 1.62 kGy(SiO<sub>2</sub>) LOCId laser driver shows degradation









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#### Co-60 TID on MTX LOCId

Co-60 varying dose-rates 0.14 to 45 Gy/hr Irradiation in daytime, annealing overnight Dose calibration using Alanine









#### Co-60 TID on MTX LOCId

Co-60 lower rate to X-ray, mio VCSEL not effected by TID CMOS current drops ~ 10-100 Gy(SiO<sub>2</sub>)





## VCSEL rad-hard degradation, annealing

VCSEL light degradation → linear to fluence rad-hard fiber connected to readout, independent of flux rate

Fast annealing by charge injection at operation current (10 nA) applied



#### NIEL to GaAs diodes

*Laser diodes* (850 nm VCSELs, 1 Gbps) NIEL damage

→ light degradation linear to fluence Higher proton momentum

→ less damage to GaAs components (contrary to theoretical calculations)





#### LANSCE neutron test

- Beam profile similar to ATLAS

- USB transceiver in Bit-Err-Rate Straitix II GX, PRBS 2<sup>7</sup>-1 bit pattern TX path, RX path tested separately

neutron flux  $2.9 \times 10^5$  n/cm<sup>2</sup>s over 1.5 days to  $3.8 \times 10^{10}$  n/cm<sup>2</sup>

TX: 0 error, upper limit 1.0×10<sup>-10</sup> cm<sup>2</sup>/ch (95% CL)

RX: 11 errors SEE cross section 2.9×10<sup>-10</sup> cm<sup>2</sup>/ch







# ATLAS ITK 1<sup>st</sup> optical link

- VCSEL 850 nm matched to Epi Si PIN diodes.
- Iow thresholds (~3 mA).
- Very radiation hard



# 1 RX PIN + DORIC 2 TX VCSEL + VDC

➢ 45° fibre-end mirror







#### ATLAS Phase-I LAr transceivers

- ~ 5k transceivers produced by AS TW opto-electronic companies
- Quality Assurance, Quality Contract at AS: every channel measured for Chip test, TOSA L-I, eye-diagram, Bit-Error-Rate, Burn-in eye-diagram parameters well within specification







## The CERN Phase-II VTRx+ (FOCI 上詮)

- CERN Versatile Link+ group → one module for all
- 10x20 mm<sup>2</sup> height 2.5mm, 4.5mm
- 4TX+1RX, 10Gbps TX, 2.56 Gbps RX
- VCSEL array laser driver LQD, TSMC 65nm
- Optical Receiver GBTIA TSMC 65nm
- production 65K pcs
- Lens is the TW Orange-tek



Orange-tek OT-12, OT-13



#### TWEPP2021, C. Soos PIN SERDES SERDES SERDES FPGA Passives **IpGBT** or other SERDES LDD (array) array **On-Detector Off-Detector Custom Electronics & Packaging** Commercial Off-The-Shelf (COTS) **Radiation Hard** Custom Protocol

# Light coupling Technology

 Light Peak example, Intel technology delivers high bandwidth starting at 10 Gb/s to mainstream computing and consumer electronics



# AS+SMU+前鼎: 25 Gbps Transmitter

- 25 Gbps components, PCB, connectors
- Driver, LOCId65, TSMC 65nm











## AS+SMU+前鼎 QTRx Transceiver

- 4TX+4RX, tested @10G, will do 25 Gbps
- VCSEL, PD, PCB all 25 Gbps qualified
- Driver, QLDD, QTIA, TSMC 65nm

QTRx	QLDD	QTIA	
Data rate	10 Gbps	2.56 Gbps	10 Gbps
Power supply	1.2 V and 2.5 V		
Sensitivity (BER =1E-12)	80 mV	-17 dBm	-8 dBm
Rise /fall time	37 ps	40 ps	50 ps
Total jitter (BER =1E-12)	-	38.5 ps	52.4 ps
Power consumption /ch	124 mW	120 mW with CP	

# Tested 20 × 10 × 5 mm<sup>3</sup>



#### RX@10Gbps



#### TX@10Gbps





- Opto module assembly is mature industry ASIC packaged, wire-bonding Electric connectors: SFP, QSFP, Hirose, Firefly Optical coupling: MT, pigtail mini-formfactor
- TSMC 65 is 25 Gbps ready SIMC 55 re-freshing, 25 Gbps expected
- Radiation hardness NIEL on 25 Gbps VCSEL, PD TID, SEE on CMOS